

AMENDMENTS TO THE CLAIMS

Claim 1 (currently amended) An electronic circuit device comprising:

an electronic component having a connection terminal on one side thereof;

a circuit board having an electrode pad thereon;

an adhesive sheet having a through-hole, with a cross-sectional area of said electrode pad being greater than a cross-sectional area of said through-hole; and

a conductive adhesive provided in said through-hole;

wherein said electronic component and said circuit board are bonded to each other via said adhesive sheet, and said connection terminal on said electronic component and ~~an~~ said electrode pad on said circuit board are bonded to each other by said conductive adhesive in said through-hole.

Claim 2 (previously presented) The electronic circuit device according to claim 1, wherein at least one of said connection terminal and said electrode pad protrude into said through-hole.

Claim 3 (previously presented) The electronic circuit device according to claim 1, wherein said circuit board comprises a polymeric resin sheet.

Claim 4 (previously presented) The electronic circuit device according to claim 3, wherein said polymeric resin sheet is made of a material selected from the group consisting of polyethylene terephthalate, acrylnitrile-butadiene-styrene, polycarbonate, and polyimide.

Claim 5 (previously presented) The electronic circuit device according to claim 1, wherein said conductive adhesive is a conductive paste consisting essentially of conductive particles and a thermosetting resin binder.

Claim 6 (previously presented) The electronic circuit device according to claim 1, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

Claim 7 (previously presented) The electronic circuit device according to claim 1, wherein said conductive adhesive essentially consists of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

Claim 8 (withdrawn) A method of manufacturing an electronic circuit device, comprising:
bonding an adhesive sheet to a circuit board so that a through-hole, through said adhesive sheet, is aligned with an electrode pad provided on a surface of said circuit board;
providing a conductive adhesive in said through-hole; and
bonding a connection terminal, provided on one side of an electronic component, to said electrode pad on said circuit board via said conductive adhesive in said through-hole, and bonding said electronic component to said adhesive sheet.

Claim 9 (withdrawn) The method according to claim 8, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

Claim 10 (withdrawn) The method according to claim 8, wherein said conductive adhesive consists essentially of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.